

**ON Semiconductor®** 

# FDMS5361L-F085

## N-Channel PowerTrench<sup>®</sup> MOSFET 60 V, 35 A, 15 m $\Omega$

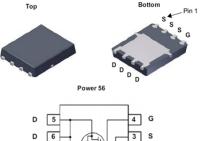
#### Features

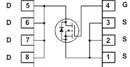
- Typ r<sub>DS(on)</sub> = 11.7 mΩ at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 16.5 A
- Typ Q<sub>g(tot)</sub> = 37 nC at V<sub>GS</sub> = 10 V, I<sub>D</sub> = 16.5 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

#### Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems







For current package drawing, please refer to the our website at www.onsemi.com

### **MOSFET Maximum Ratings** T<sub>J</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Ratings	Units		
V <sub>DSS</sub>	Drain to Source Voltage		60	V	
V <sub>GS</sub>	Gate to Source Voltage		±20	V	
I <sub>D</sub>	Drain Current - Continuous (V <sub>GS</sub> =10) (Note 1)	T <sub>C</sub> =25°C	35	^	
	Pulsed Drain Current	T <sub>C</sub> = 25°C	See Figure4	Α	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	82	mJ	
PD	Power Dissipation		75	W	
	Derate above 25°C		0.5	W/ºC	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.0	°C/W	
$R_{\thetaJA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	50	°C/W	

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS5361L	FDMS5361L-F085	Power 56	13"	12mm	3000 units

Notes:

2: Starting  $T_J = 25^{\circ}$ C, L = 0.21mH,  $I_{AS} = 28$ A,  $V_{DD} = 60$ V during inductor charging and  $V_{DD} = 0$ V during time in avalanche.

3:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

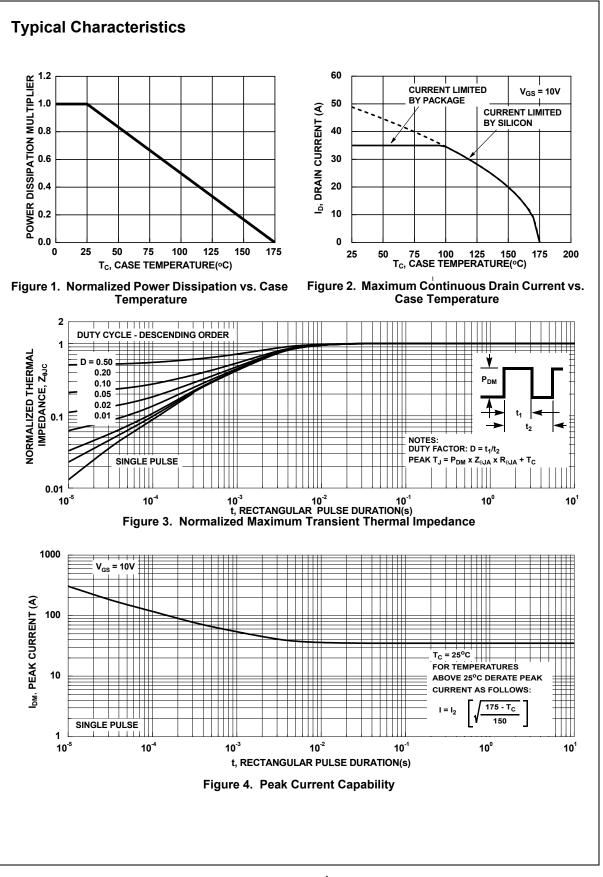
<sup>1:</sup> Current is limited by junction temperature.

Off Cha		Test	Conditions	Min.	Тур.	Max.	Units		
Bunse	Off Characteristics								
VLUGO	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250μA, V	′ <sub>GS</sub> = 0V	60	-	-	V		
		V <sub>DS</sub> =60V,	$T_J = 25^{\circ}C$	-	-	1	μA		
IDSS	Drain to Source Leakage Current	$V_{GS} = 0V$	$T_{J} = 175^{\circ}C(Note 4)$	-	-	1	mA		
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS}$ = ±20V		-	-	±100	nA		
On Cha	racteristics								
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub>	<sub>D</sub> = 250μA	1.0	1.84	3.0	V		
		I <sub>D</sub> = 16.5A,	T <sub>J</sub> = 25 <sup>o</sup> C	-	11.7	15	mΩ		
D	Drain to Source On Resistance	V <sub>GS</sub> = 10V	$T_{J} = 175^{\circ}C(Note 4)$	-	24.5	30	mΩ		
R <sub>DS(on)</sub>		I <sub>D</sub> = 16.5A,	$T_J = 25^{\circ}C$	-	14.6	18	mΩ		
		V <sub>GS</sub> = 4.5V	T <sub>J</sub> = 175 <sup>o</sup> C(Note 4)	-	29.5	34	mΩ		
Dynami	c Characteristics	L	<u> </u>						
•					1080				
C <sub>iss</sub>	C Characteristics	- V <sub>DS</sub> = 25V, V		-	1980 176	-	pF pF		
C <sub>iss</sub> C <sub>oss</sub>	Input Capacitance						•		
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance		<sub>GS</sub> = 0V,	-	176	-	pF		
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> R <sub>g</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	f = 1MHz		-	176 93	-	pF pF		
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> R <sub>g</sub> Q <sub>g(ToT)</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance	f = 1MHz f = 1MHz	V V <sub>DD</sub> = 30V	-	176 93 1.6		pF pF Ω		
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> R <sub>g</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance Total Gate Charge at 10V	f = 1MHz f = 1MHz V <sub>GS</sub> = 0 to 10	V V <sub>DD</sub> = 30V	- - -	176 93 1.6 37	- - - 44	pF pF Ω nC		

$V_{SD}$	Source to Drain Diode Voltage	I <sub>SD</sub> = 16.5A, V <sub>GS</sub> = 0V	-	-	1.25	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 16.5A, dI <sub>SD</sub> /dt = 100A/μs,	-	28	32	ns
Q <sub>rr</sub>	Reverse Recovery Charge	V <sub>DD</sub> =48V	-	25	33	nC

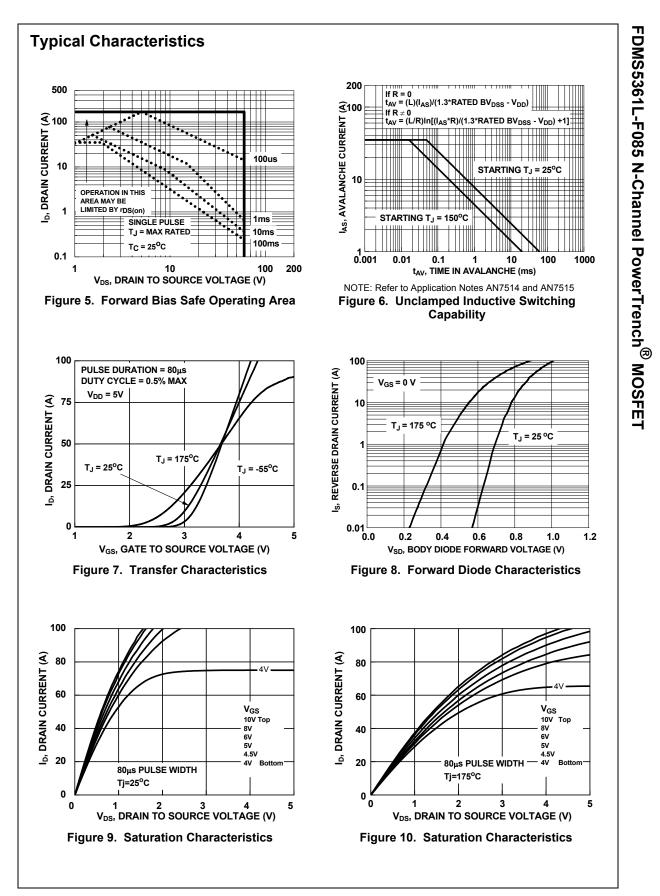
Note:

4: The maximum value is specified by design at  $T_J = 175^{\circ}$ C. Product is not tested to this condition in production.

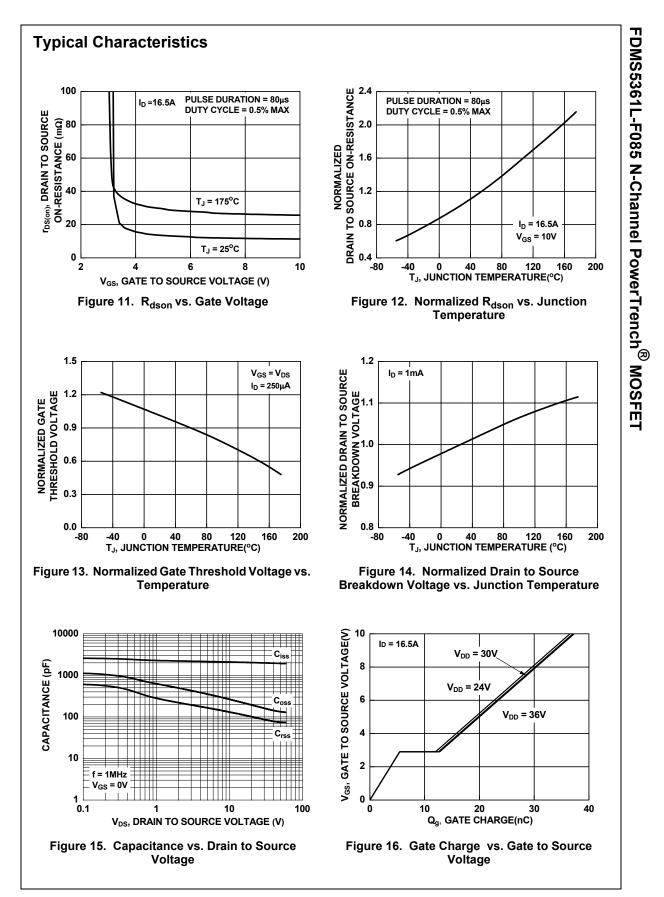


FDMS5361L-F085 N-Channel PowerTrench<sup>®</sup> MOSFET

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